

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **08/28/2022**

Details for "DS30BA101SQX/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
DS30BA101SQX/NOPB	SN	Level-3-260C-168 HR	Texas Instruments Electronics	RUM 16	4 x 4 x 0.75	35.1

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.243413	98.734049	987340	0.693184	6932
Nickel and Its Alloys	Nickel	7440-02-0	0.000001	0.000406	4	0.000003	0
Not Categorized	Proprietary Materials		0.000027	0.010952	110	0.000077	1
Precious Metals	Gold	7440-57-5	0.000053	0.021498	215	0.000151	2
Precious Metals	Palladium	7440-05-3	0.003033	1.230256	12303	0.008637	86
Precious Metals	Silver	7440-22-4	0.000007	0.002839	28	0.00002	0
Sub-Total			0.246534	100	1000000	0.702072	7021
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.139447	75.000134	750001	0.397113	3971
Thermoplastics	Epoxy	85954-11-6	0.046482	24.999866	249999	0.13237	1324
Sub-Total			0.185929	100	1000000	0.529483	5295
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	15.28016	95.842439	958424	43.51438	435144
Copper and Its Alloys	Iron	7439-89-6	0.37632	2.360409	23604	1.071673	10717
Copper and Its Alloys	Phosphorus	7723-14-0	0.004704	0.029505	295	0.013396	134
Copper and Its Alloys	Zinc	7440-66-6	0.018816	0.11802	1180	0.053584	536
Precious Metals	Silver	7440-22-4	0.263	1.649627	16496	0.748963	7490
Sub-Total			15.943	100	1000000	45.401996	454020
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.929	100	1000000	2.645578	26456
Sub-Total			0.929	100	1000000	2.645578	26456
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	15.695666	90.500002	905000	44.697646	446976
Other Plastics and Rubber	Carbon Black	1333-86-4	0.086716	0.499998	5000	0.246947	2469
Thermoplastics	Epoxy	85954-11-6	1.560895	9	90000	4.44507	44451
Sub-Total			17.343277	100	1000000	49.389663	493897
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.467456	100	1000000	1.331207	13312
Sub-Total			0.467456	100	1000000	1.331207	13312
Total			35.115196			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component level** and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq888>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.